

Application Serial No. 10/632,273
Response to September 7, 2004 OA

MI22-2379

In the Specification

At p. 1 before the "Technical Field" section, please amend the paragraph as shown below:

RELATED PATENT DATA

This patent application is a divisional application of U.S. Patent Application Serial No. 10/057,711, filed January 24, 2002, now U.S. Patent No. 6,670,819, which is a divisional application of U.S. Patent Application Serial No. 09/411,139, filed October 1, 1999, now U.S. Patent No. 6,657,450 B2, which is a divisional application of U.S. Patent Application Serial No. 09/267,990, filed March 12, 1999, now U.S. Patent No. 6,380,754 B1, which is a divisional application of U.S. Patent Application 08/895,764, filed July 17, 1997, now U.S. Patent No. 6,127,195, which is a continuation of U.S. Patent Application Serial No. 08/621,157, filed March 21, 1996, since abandoned; which is a continuation of U.S. Patent Application Serial No. 08/206,747, filed March 4, 1994, now U.S. Patent No. 5,523,697, which is a divisional of U.S. Patent Application Serial No. 08/116,394, filed September 3, 1993, now U.S. Patent No. 5,326,428, the disclosures of which are incorporated by reference.

Page 4, lines 17-18 replace the paragraph as follows:

Fig. 18 is a view of a substrate fragment processed ~~in~~ in accordance with the invention.

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The paragraph beginning at line 22 on page 13 has been amended as shown below:

The illustrated projecting apexes actually project in to half-way into the thickness of the bonding pads, a distance of approximately ~~on-half~~ one-half "A". The penetration stop surface 62 described with reference to Fig. 5 provides a stopping point for preventing the projecting points from extending further into bonding pads 88 than would be desired. In connecting the testing apparatus to chip 85, pressure would be monitored during engagement of the projecting tips relative to the pads 88. At some point during the projection, the force or back pressure against the testing apparatus would geometrically increase as the penetration stop plane reaches the outer surface of the bonding pads 88, indicating that full penetration had occurred. At this point, the testing substrate and chip 85 would be effectively electrically engaged. An electric signal would be sent between the respective grouping of apexes and respective test pads in conventional testing methods to evaluate operability of integrated circuitry formed within the semiconductor substrate 85.